

ABSTRACT OF THE DISCLOSURE

A fabrication method of a semiconductor integrated circuit device including polishing the entire area of an edge of a wafer, for example, by using three polishing drums in which a polishing drum polishes the upper surface of the edge of the wafer relatively, the polishing drum polishes the central portion of the edge of the wafer relatively and a polishing drum polishes the lower surface of the edge of the wafer relatively, thereby preventing occurrence of obstacles which cause defoliation of thin films on the edge of the wafer.